# ANNOUNCEMENT

The Third Thermal Expansion Symposium will be held in Corning, New York, October 27–29, 1971 sponsored jointly by the Department of Physics, University of Toronto and Corning Glass Works. The Symposium provides an opportunity to exchange new ideas and applied studies of thermal expansion. Contributed papers are solicited on basic experimental and theoretical investigations of thermal expansion, on the relation of thermal expansion to other properties, on the technology of low expansion and of composite materials, on studies at extreme high or low temperatures, on thermal effects in diffraction studies, and on thermal expansion standards. A number of invited papers will be presented by leading scientists and engineers. An exhibit by manufacturers of thermal expansion equipment is planned. Plans for publication of the proceedings are incomplete at this date. Deadline for receipt of abstracts is June 30, 1971, to be submitted to:

Dr. G. M. GRAHAM
Department of Physics
University of Toronto
Toronto, Ontario, Canada

Additional information may be obtained from:

Mr. H. E. HAGY
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Corning, New York 14830